

REMARKS

Claims 1, 2, 4 through 8, 10 through 14, 16 through 20, and 22 through 24 are currently pending in the application.

This amendment is in response to the Office Action of August 8, 2007.

35 U.S.C. § 112 Claim Rejections

Claim 10 is rejected under 35 U.S.C. § 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which Applicants regard as the invention.

Applicants have amended the claimed invention for the presently claimed invention to particularly point out and distinctly claim the subject matter of the invention to comply with the provisions of 35 U.S.C. § 112. Therefore, presently amended claim 10 is allowable under the provisions of 35 U.S.C. § 112.

35 U.S.C. § 102(b) Anticipation Rejections

Anticipation Rejection Based on Sakaki et al. (U.S. Patent Publication No. 2003/0017652)

Claims 1, 2, 4 through 8, 10 through 14, 16 through 20, and 22 through 24 were rejected under 35 U.S.C. § 102(b) as being anticipated by Sakaki et al. (U.S. Patent Publication No. 2003/0017652).

Applicants assert that a claim is anticipated only if each and every element as set forth in the claim is found, either expressly or inherently described, in a single prior art reference. *Verdegaal Brothers v. Union Oil Co. of California*, 2 USPQ2d 1051, 1053 (Fed. Cir. 1987). The identical invention must be shown in as complete detail as is contained in the claim. *Richardson v. Suzuki Motor Co.*, 9 USPQ2d 1913, 1920 (Fed. Cir. 1989).

Applicants assert that the Sakai et al. reference does not and cannot anticipate the claimed inventions of presently amended independent claims 1, 7, 13, and 19 under 35 U.S.C. § 102 because the Sakai et al. reference does not identically describe, either expressly or inherently, each and every element of the claimed invention in as complete detail as is contained in the claim.

Turning to the cited prior art, the Sakai et al. reference describes a semiconductor chip 1 having a resin film bonded to a back surface 1Y of the chip 1 wherein the resin film is a thermosetting resin of the epoxy group.

Applicants assert that the thermosetting resin of the epoxy group as a resin film of the Sakai et al. reference does not describe the elements of the claimed inventions of presently amended independent claims 1, 7, 13, and 19 calling for “a force-balancing layer covering at least a portion of the back side, the force-balancing layer for balancing a portion of the force on the front side, the force-balancing layer comprising at least one of a metal, a metal alloy, a metallorganic material, a photoresist material, a multifilm layer material remaining as a multilayer material having independent layers for balancing stresses omnidirectionally when balancing the tensile and compressive stresses of the semiconductor substrate, a multilayer tape material remaining as a multilayer material having independent layers for balancing stresses omnidirectionally, an adhesive material having reinforcement materials therein, a temporary adhesive material having reinforcing material therein, and a chemical vapor deposition material”. Applicants assert that the thermosetting resin of the epoxy group as a resin film of the Sakai et al. reference does not describe a metal. Applicants assert that the thermosetting resin of the epoxy group as a resin film of the Sakai et al. reference does not describe a metal alloy. Applicants assert that the thermosetting resin of the epoxy group as a resin film of the Sakai et al. reference does not describe a metallorganic material. Applicants assert that the thermosetting resin of the epoxy group as a resin film of the Sakai et al. reference does not describe a multifilm layer material for balancing stresses omnidirectionally. Applicants assert that the thermosetting resin of the epoxy group as a resin film of the Sakai et al. reference does not describe a multilayer tape material remaining as a multilayer material having independent layers for balancing stresses omnidirectionally. Applicants assert that the thermosetting resin of the epoxy group as a resin film of the Sakai et al. reference does not describe a multilayer tape material remaining as a multilayer material having independent layers for balancing stresses omnidirectionally. Applicants assert that the thermosetting resin of the epoxy group as a resin film of the Sakai et al. reference does not describe an adhesive material having reinforcement materials therein. Applicants assert that the thermosetting resin of the epoxy group as a resin film of the Sakai et al.

reference does not describe a temporary adhesive material having reinforcing material therein. Applicants assert that the thermosetting resin of the epoxy group as a resin film of the Sakai et al. reference does not describe a chemical vapor deposition material. Applicants assert that the thermosetting resin of the epoxy group as a resin film of the Sakai et al. reference does not describe an adhesive layer comprises a layer of markable material including one at least one of a UV acrylic, thio-phenic material, poly-paraxylylene material, urethane material, silicone material and acrylic material for laser-marking.

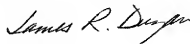
Applicants assert that, at best, the Sakai et al. reference describes a thermosetting resin of the epoxy group as a resin film which applied in layers are thermally hardened to convert the layers to a single layer of resin film. Applicants assert that such a description is not any of the claimed inventions of presently amended independent claims 1, 7, 13, and 19 whatsoever.

Therefore, presently amended independent claims 1, 7, 13, and 19 are allowable as well as the dependent claims therefrom.

Applicants submit that claims 1, 2, 4 through 8, 10 through 14, 16 through 20, and 22 through 24 are clearly allowable over the cited prior art.

Applicants request the allowance of claims 1, 2, 4 through 8, 10 through 14, 16 through 20, and 22 through 24 and the case passed for issue.

Respectfully submitted,



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